Preferred Device

SWITCHMODE™ Power Rectifier

D²PAK Surface Mount Power Package

Employs the use of the Schottky Barrier principle with a platinum barrier metal. These state-of-the-art devices have the following features:

- Package Designed for Power Surface Mount Applications
- Center-Tap Configuration
- Guardring for Stress Protection
- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Short Heat Sink Tab Manufactured Not Sheared!
- Similar in Size to Industry Standard TO-220 Package

Mechanical Characteristics

- Case: Epoxy, Molded, Epoxy Meets UL 94 V-0
- Weight: 1.7 grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 50 Units per Plastic Tube
- Available in 24 mm Tape and Reel, 800 units per 13" reel by adding a "T4" suffix to the part number
- Device Meets MSL1 Requirements
- ESD Ratings: Machine Model, C (>400 V)

Human Body Model, 3B (>8000 V)

MAXIMUM RATINGS (Per Leg)

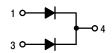
Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	60	V
Average Rectified Forward Current (Rated V_R , $T_C = 110^{\circ}C$) Total Device		10 20	А
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz, T _C = 100°C)	I _{FRM}	20	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	150	Α
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)	I _{RRM}	0.5	А
Storage Temperature Range	T _{stg}	-65 to +175	°C
Operating Junction Temperature	T _J	-65 to +150	°C
Voltage Rate of Change (Rated V _R)	dv/dt	10,000	V/μs



ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 20 AMPERES 60 VOLTS



MARKING DIAGRAM





D²PAK CASE 418B STYLE 3

B2060T = Specific Device Code

ORDERING INFORMATION

Device	Package Shipping [†]	
MBRB2060CT	D ² PAK	50/Rail
MBRB2060CTT4	D ² PAK	800/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Thermal Resistance - Junction-to-Case - Junction-to-Ambient (Note 1)	$R_{ heta JC} \ R_{ heta JA}$	2.0 50	°C/W

ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 2) ($i_F = 20 \text{ Amps}, T_J = 125^{\circ}\text{C}$) ($i_F = 20 \text{ Amps}, T_J = 25^{\circ}\text{C}$)	V _F	0.85 0.95	Volts
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_J = 125^{\circ}C$) (Rated dc Voltage, $T_J = 25^{\circ}C$)	i _R	35 0.15	mA

- 1. When mounted using minimum recommended pad size on FR-4 board.
- 2. Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

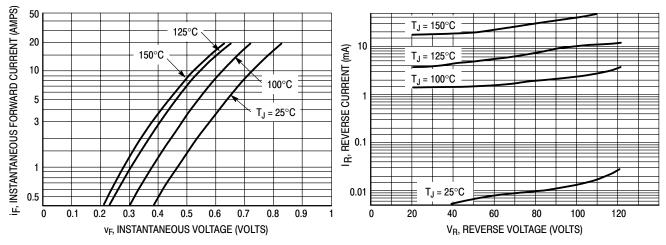


Figure 1. Typical Forward Voltage Per Diode

Figure 2. Typical Reverse Current Per Diode

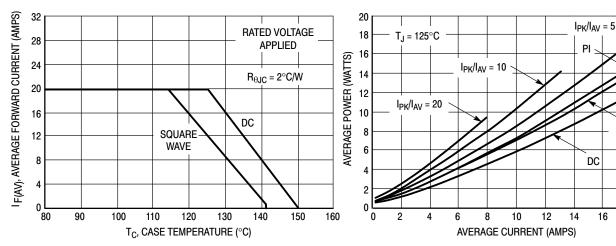


Figure 3. Typical Current Derating, Case, Per Leg

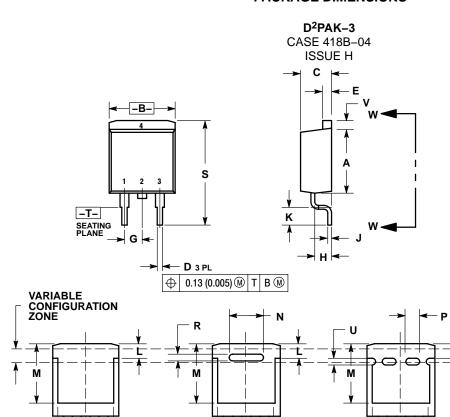
Figure 4. Average Power Dissipation and Average Current

SQUARE

WAVE

18 20

PACKAGE DIMENSIONS



VIEW W-W

VIEW W-W

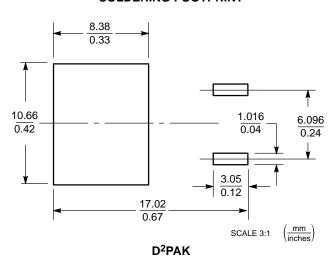
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
М	0.280	0.320	7.11	8.13
N	0.197 REF		5.00 REF	
Р	0.079 REF		2.00 REF	
R	0.039	REF	0.99 REF	
S	0.575	0.625	14.60	15.88
٧	0.045	0.055	1.14	1.40

- STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

SOLDERING FOOTPRINT

VIEW W-W



SWITCHMODE is a trademark of Semiconductor Components Industries, LLC.

ON Semiconductor and was are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.